

<b>Company</b>		<b>DUNS#</b>	<b>URL For Additional Information</b>
National Semiconductor		04-147-2986	<a href="http://www.national.com/analog/quality/green">http://www.national.com/analog/quality/green</a>

<b>Contact</b>	<b>Title</b>	<b>Phone</b>	<b>Email</b>
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<b>Part Number</b>	<b>MSL Rating</b>	<b>Peak Body Temp C</b>	<b>MaxTime(Sec)</b>	<b>Cycles</b>	<b>Unit Type</b>
LM8333	1	260	40	4	Each

<b>Document Date</b>	European RoHS Compliant. China RoHS Compliant.	<b>Weight (mg)</b>	Does NOT Contain Halogens
10-27-2011		33.44	

### Material Composition Declaration for Electronic Products

Item	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Leadframe	7.012	Cu	7440-50-8	6.966	993,500	208,288
		Cr	7440-47-3	0.021	3,000	628
		Sn	7440-31-5	0.018	2,500	538
		Zn	7440-66-6	0.007	1,000	209
Solder Balls	5.119	Sn	7440-31-5	5.032	983,000	150,460
		Ag	7440-22-4	0.061	12,000	1,824
		Cu	7440-50-8	0.026	5,000	777
Plastic	18.909	SiO2	60676-86-0	16.735	885,000	500,389
		Epoxy Resin	25928-94-3	1.607	85,000	48,050
		Mg(OH)2	1309-42-8	0.567	30,000	16,954
Chip	1.370	Si	7440-21-3	1.362	994,000	40,725
		Al	7429-90-5	0.008	6,000	239
Wires	0.487	Au	7440-57-5	0.487	1,000,000	14,562
LeadFinish	0.267	Sn	7440-31-5	0.267	1,000,000	7,983
Die Attach	0.143	SiO2	60676-86-0	0.057	400,000	1,704
		Synthetic Rubber	64706-29-2	0.043	300,000	1,286
		Epoxy Resin	25928-94-3	0.043	300,000	1,286
Int. LeadFinish	0.137	Ag	7440-22-4	0.137	1,000,000	4,096

**Note:** The device content disclosed herewith is approximate and is based on engineering estimates only. It has not been verified through analytical testing.

Additionally, the following should be noted:

- One or more dopant materials may be present in the silicon die at sub-ppm levels to provide semiconductor properties.
- Epoxy resin components listed are generic and may or may not be the specific compound used, which is considered proprietary.

### RoHS Material Composition Declaration

<b>RoHS Directive 2002/95/EC</b>	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

- National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7(a) or 7(c)-I.
- National products do not contain and are not manufactured with ozone depleting compounds.
- National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
- National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
- National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. Nationals Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION.

  
John L. Conn  
Vice President Quality

**Banned Substance Monitoring**

<b>Part Number</b>	<b>Document Date</b>
LM8333	10-27-2011

European RoHS Compliant.

China RoHS Compliant.

<b>Item#</b>	<b>Material</b>	<b>Cd</b>	<b>CrVI</b>	<b>Pb</b>	<b>Hg</b>	<b>PBB</b>	<b>PBDE</b>	<b>Cl</b>	<b>Br</b>	<b>Ref#</b>
1	CHIP	<1	<1	<1	<30	<10	<10	<75	<50	1000
2	COMPOUND	<2	<2	<2	<2	<5	<5	<50	<50	649
3	FILM	<2	<2	<2	<2	<5	<5	120	<50	626
4	FRAME	<2	N/D	<2	<2	<5	<5	N/A	N/A	628
5	SOLDER BAL	<2	N/D	194	<2	<5	<5	<50	<50	684
6	WIRE	<2	N/D	<2	<2	<5	<5	N/A	N/A	75

\* Cd: Cadmium, CrVI: Hexavalent Chromium, Pb: Lead, Hg: Mercury, NA: Not Applicable

\* Unless otherwise noted, units are in PPM (parts-per-million)

<b>Ref#</b>	<b>3rd Party Analysis</b> (available upon request, subject to a non-disclosure agreement)
1000	Analysis on 01/24/2011 by Balazs as per Report# 11-00322-00
649	Analysis on 04/29/2011 by SGS per Report# LPCI/04386(B)/11
626	Analysis on 04/29/2011 by SGS per Report# LPCI/04401(B)/11
628	Analysis on 04/29/2011 by SGS per Report# LPCI/04377(B)/11
684	Analysis on 04/29/2011 by SGS per Report# LPCI/04391(B)/11
75	Analysis on 04/29/2011 by SGS per Report# LPCI/04464(B)/11